L Number	Hits	Search Text	DB	Time stamp
1	77641	356/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:14
2	0	356/$.ccls. and dielectric adj3 viod	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:14
3	1	356/$.ccls. and dielectric adj3 void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:14
4	16	356/$.ccls. and layer adj3 void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 07:59
5	4759	356/237.1-237.5.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 07:59
6	1	356/237.1-237.5.ccls. and layer adj3 void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:00
7	153	356/237.1-237.5.ccls. and void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:15
8	76	(356/237.1-237.5.ccls. and void) and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:15
9	24	((356/237.1-237.5.ccls. and void) and layer) and dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:16
10	104682	250/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:14
11	0	250/$.ccls. and dielectric adj3 viod	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:14
12	6	250/$.ccls. and dielectric adj3 void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:15
13	1520	250/$.ccls. and void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:15
14	863	(250/$.ccls. and void) and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:15

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15	250	((250/$.ccls. and void) and layer) and dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:16
16	745674	processor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:16
17	58	(((250/$.ccls. and void) and layer) and dielectric) and processor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:17
18	221	(((250/$.ccls. and void) and layer) and dielectric) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:17
19	52	((((250/$.ccls. and void) and layer) and dielectric) and (wafer or substrate)) and processor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:17
-	2	("6134002").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:20
-	77564	356/$.CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 15:48
-	935	((356/$).CCLS.) and ((wafer or substrate) adj3 (tilt or angle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 15:48
-	2	("6556290").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:35
-	0	(356/$.ccls. and dielectric adj3 void) and ((beam adj2 splitter) or (beamsplitter))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 15:06
-	0	(356/$.ccls. and layer adj3 void) and reflected	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:46
-	0	(356/$.ccls. and dielectric adj3 viod) and ((wafer or substrate) adj3 (tilt))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 15:06
-	0	(356/237.1-237.5.ccls. and layer adj3 void) and ((beam adj2 splitter) or (beamsplitter))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 15:21
-	0	(356/$.ccls. and dielectric adj3 void) and 356/138-155.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 15:22